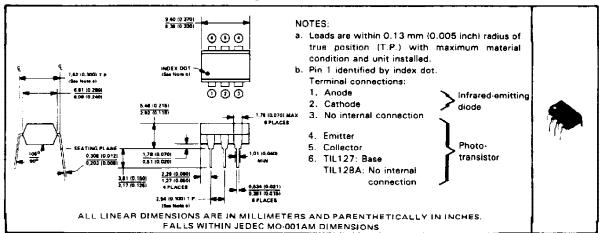
- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Darlington-Connected Phototransistor
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- High-Voltage Electrical Isolation . . . 5000-Volt Rating
- Plastic Dual-In-Line Package
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers
- No Base Connection on TIL128A for Environments with High Electromagnetic Interference

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation, and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage
Collector-Base Voltage (TIL127)
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter-Base Voltage (TIL127)
Input-Diode Reverse Voltage
Input-Diode Continuous Forward Current
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 2)
Phototransistor (See Note 3)
Total (Infrared-Emitting Diode plus Phototransistor, See Note 4)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 Inch) from Case for 10 Seconds

NOTES: 1. This value applies when the base-emitter diode is open-circuited.

- 2. Denate linearly to 100°C free-air temperature at the rate of 2 mW/ $^{\circ}\text{C}$.
- 3. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.
- 4. Denate linearly to 100°C free-air temperature at the rate of 3.33 mW/°C.

TEXAS INSTRUMENTS

TIL127, TIL128A OPTOCOUPLERS

electrical characteristics at 25°C free-air temperature

PARAMETER		7507	CONDITIONS	+	TIL127			TIL128A			UNIT
		1681	CONDITIONS	MIN TYP MAX		MIN	TYP	MAX	DIVIT		
V(BR)C80	Collector-Base Breakdown Voltage	I _C = 10 μA,	I _E = 0,	le = 0	30						٧
V(BRICEO	Collector-Emitter Breakdown Voltage	I _C = 1 mA,	I _B = 0.	IF = 0	30			30			٧
Vівятево	Emitter-Base Breakdown Voltage	IE = 10 μA,	IC = 0'	1 _F = 0	7						>
V(BR)ECO	Emitter-Collector Breakdown Voltage	I _E = 10 μA,	iF = 0					7			٧
I _R	Input Diode Static Reverse Current	VH = 3 V					10			10	μА
	On-State	V _{CE} = 1 V,	1g = 0,	Ip = 10 mA	30	100				mΑ	
(Clan)	Collector Current	V _{CE} = I V,	IF = 10 mA					30	160		1 '''^
IC(off)	Off-State Collector Current	V _{CE} = 10 V,	I _B = 0,	IF = 0			100		·	100	n A
hFE	Transistor Static Forward Current Transfer Ratio	V _{CE} = 1 V,	I _C 10 mA,	IF = 0	1	15 000					
٧ _E	Input Diode Static Forward Voltage	I _F = 10 mA					1.5			1.5	٧
	Collector-Emitter	I _C 125 mA,	IB = 0,	1 _F = 50 mA			1.2	1			V
VCE(sat)	Saturation Voltage	IC = 30 mA,	IF = 10 mA				···	T -		1	· ·
rio	Input-to-Output Internal Resistance	V _{in-out} = 500 V,	See Note 5		1011			1011			Ω
C _{io}	Input-to-Output Capacitance	V _{in-out} = 0,	f = 1 MHz,	See Note 5		1	1.3		1	1.3	pF

NOTE 5: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together. † References to the base are not applicable to the TIL128A.

switching characteristics at 25°C free-air temperature

PARAMETER		TER	T CONDITIONS†	TIL127		7	TIL128A			UNIT
		169	I CONDITIONS.	MIN TYP MAX N			MIN	TYP	MAX]
tr	Rise Time	V _{CC} = 15 V,	I _{C(оп)} = 125 mA,		300					
tf	Fall Time	R _L = 100 Ω,	See Figure 1		300					μs
tŗ	Rise Time	V _{CC} = 10 V,	Ic(on) = 2.5 mA,					300		
t _f	Fall Time	R _L = 100 Ω,	See Figure 1				T -	300		μ5

PARAMETER MEASUREMENT INFORMATION



- NOTES: a. The input waveform is supplied by a generator with the following characteristics: Z_{out} = 50 Ω , $\tau_r \le$ 15 ns, duty cycle \approx 1%, t $_{W}$ = 500 μ s. b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_{r} \le$ 12 ns, $R_{H} \ge$ 1 $M\Omega$, $C_{H} \le$ 20 pF



TYPICAL CHARACTERISTICS

COLLECTOR CURRENT COLLECTOR-EMITTER VOLTAGE 120 - MART COMPANION lB ≈ ų Out TA = 25°C 100 See Note 6 IC-Collector Current-mA 80 5 mA 60 40 (F = 2.5 mÅ 20 0 0 0.4 1.6 2.0 2.4 $V_{CE}-Collector\cdot Emitter\ Voltage-V$

FIGURE 2

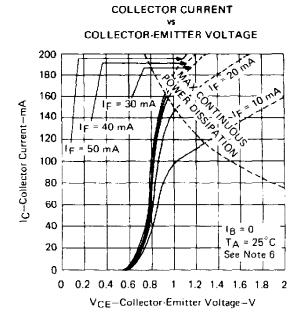
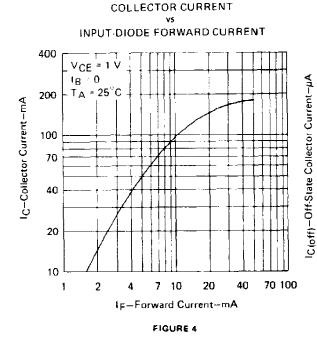


FIGURE 3



OFF-STATE COLLECTOR CURRENT
vs
FREE-AIR TEMPERATURE

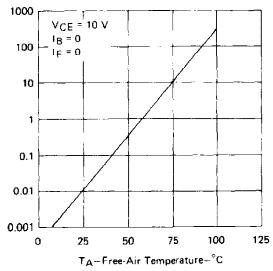


FIGURE 5

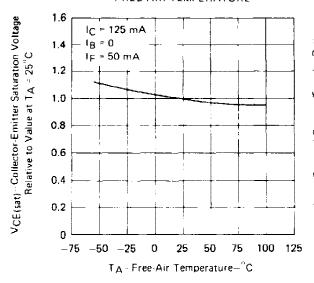
NOTE 6: Pulse operation of input diode is required for operation beyond limits shown by dotted line.



TYPICAL CHARACTERISTICS

RELATIVE COLLECTOR-EMITTER SATURATION VOLTAGE

FREE-AIR TEMPERATURE



TIL127 TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO vs

COLLECTOR CURRENT

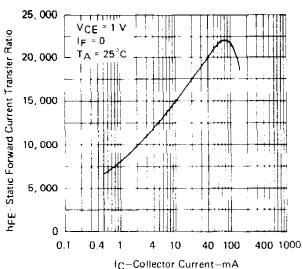
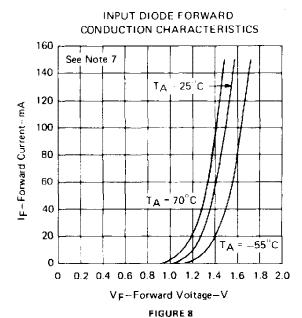


FIGURE 6

FIGURE 7



NOTE 7: This parameter was measured using pulse techniques, $t_{\rm w}$ = 1 ms, duty cycle $\leq -2\%$.



4

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PACKAGE OPTION ADDENDUM

8-Apr-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL127	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL128A	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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